



Product information

- Product name: LRI1K
- Die codes: 21 pF internal capacitance: XP2120MA

Wafer and die features

Wafer diameter	8"	
Wafer thickness	180 μm	
Die technology	F6SPs40s 3M 1P	
Diffusion Plant	Chartered	
Die identification	F37022A LRI1K	
Die finishing (front side)	SiO ₂	
Die finishing (back side)	Bare Si	
Die stepping (including X & Y scribes)	X = 1460 μm	Y = 1475 μm
Scribing street	X = 80 μm	Y = 80 μm
Bond pad size inside die	X = 90 μm	Y = 90 μm
Bond pad opening inside die	X = 70 μm	Y = 70 μm
Bond pad opening in scribe line	X = 65 μm	Y = 80 μm
Bond pad metallization	AlSiCu	
Bumping pads Ni/A	20 μm	

1 Pad extraction

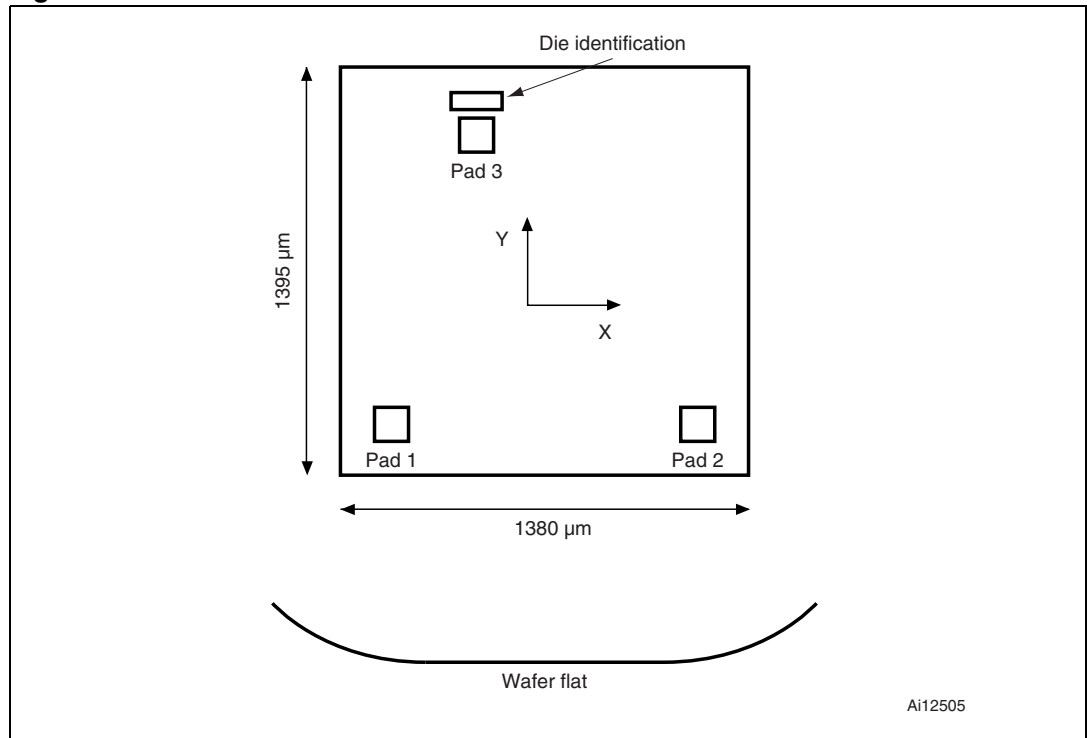
All pad placements are referred to the center of the die.
 All dimensions are given in microns, unless otherwise specified.

Table 1. Pad placements

Part number	Signal name	X	Y
1 ⁽¹⁾	AC0	-324.7	-461.9
2 ⁽¹⁾	AC1	324.7	-461.9
3	VDB	28	424.6

1. Must be connected to the coils.

Figure 1. Die identification



2 Revision history

Table 2. Document revision history

Date	Revision	Changes
26-Mar-2010	1	Initial release.

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